

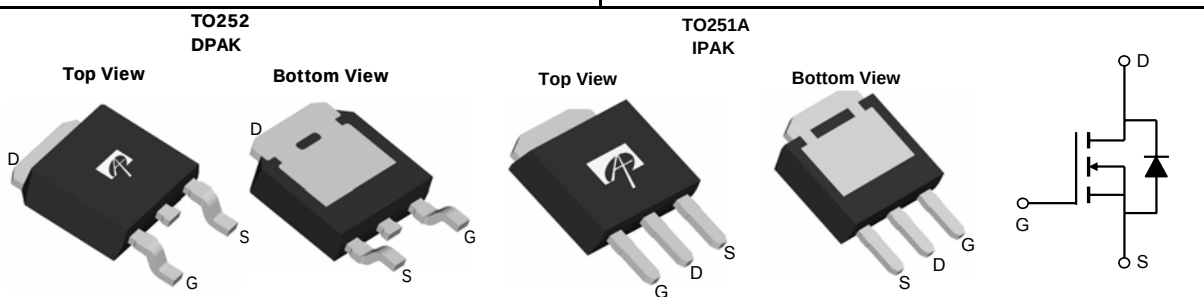
General Description

The AOD418/AOI418 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and low gate resistance. With the excellent thermal resistance of the DPAK/IPAK package, this device is well suited for high current load applications.

Product Summary

V_{DS}	30V
I_D (at $V_{GS} = 10V$)	36A
$R_{DS(ON)}$ (at $V_{GS} = 10V$)	< 7.5m Ω
$R_{DS(ON)}$ (at $V_{GS} = 4.5V$)	< 11m Ω

100% UIS Tested
 100% R_g Tested



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^G	I_D	36	A
$T_C = 25^\circ\text{C}$		28	
$T_C = 100^\circ\text{C}$			
Pulsed Drain Current ^C	I_{DM}	125	
Continuous Drain Current	I_{DSM}	13.5	A
$T_A = 25^\circ\text{C}$		10.5	
$T_A = 70^\circ\text{C}$			
Avalanche Current ^C	I_{AS}, I_{AR}	27	A
Avalanche energy $L = 0.1\text{mH}$ ^C	E_{AS}, E_{AR}	36	mJ
Power Dissipation ^B	P_D	50	W
$T_C = 25^\circ\text{C}$		25	
$T_C = 100^\circ\text{C}$			
Power Dissipation ^A	P_{DSM}	2.5	W
$T_A = 25^\circ\text{C}$		1.6	
$T_A = 70^\circ\text{C}$			
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	16	20	$^\circ\text{C/W}$
$t \leq 10\text{s}$				
Maximum Junction-to-Ambient ^{A D}	$R_{\theta JC}$	41	50	$^\circ\text{C/W}$
Steady-State				
Maximum Junction-to-Case		2.5	3	$^\circ\text{C/W}$
Steady-State				

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V T _J =55°C			1 5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} = ±20V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.5	1.95	2.5	V
I _{D(ON)}	On state drain current	V _{GS} =10V, V _{DS} =5V	125			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =20A TO252 T _J =125°C		6.2 9.5	7.5 11.5	mΩ
		V _{GS} =4.5V, I _D =20A TO252		8.5	11	mΩ
		V _{GS} =10V, I _D =20A TO251A		6.7	8	mΩ
		V _{GS} =4.5V, I _D =20A TO251A		9	11.5	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =20A		63		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.72	1	V
I _S	Maximum Body-Diode Continuous Current ^G				36	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, f=1MHz	920	1150	1380	pF
C _{oss}	Output Capacitance		125	180	235	pF
C _{rss}	Reverse Transfer Capacitance		60	105	150	pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	0.55	1.1	1.65	Ω
SWITCHING PARAMETERS						
Q _g (10V)	Total Gate Charge	V _{GS} =10V, V _{DS} =15V, I _D =20A	16	20	24	nC
Q _g (4.5V)	Total Gate Charge		7.6	9.5	11	
Q _{gs}	Gate Source Charge			2.7		nC
Q _{gd}	Gate Drain Charge			5		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =15V, R _L =0.75Ω, R _{GEN} =3Ω		6.5		ns
t _r	Turn-On Rise Time			2		ns
t _{D(off)}	Turn-Off DelayTime			17		ns
t _f	Turn-Off Fall Time			3.5		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =20A, dI/dt=500A/μs	7	8.7	10.5	ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =20A, dI/dt=500A/μs	11	13.5	16	nC

A. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_κ=25°C. The Power dissipation P_{DSM} is based on R_{θJA} and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175°C may be used if the PCB allows it.

B. The power dissipation P_D is based on T_{J(MAX)}=175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=175°C. Ratings are based on low frequency and duty cycles to keep initial T_J=25°C.

D. The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <30Qμs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=175°C. The SOA curve provides a single pulse rating.

G. The maximum current rating is package limited.

H. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_κ=25°C.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

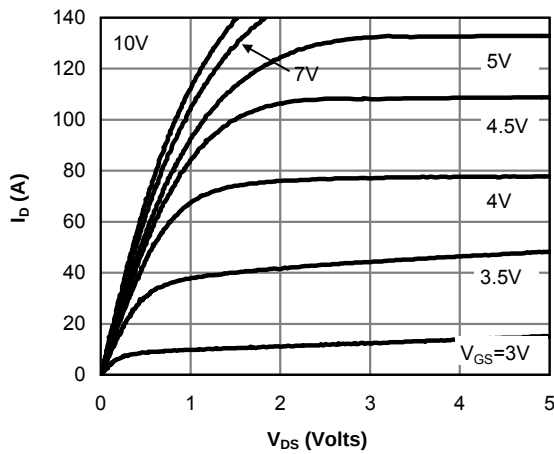


Fig 1: On-Region Characteristics (Note E)

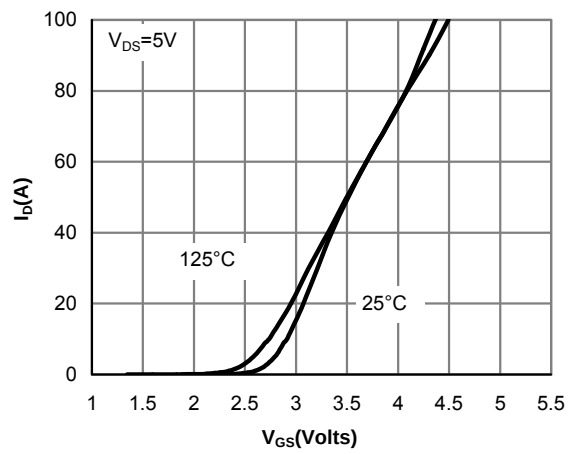


Figure 2: Transfer Characteristics (Note E)

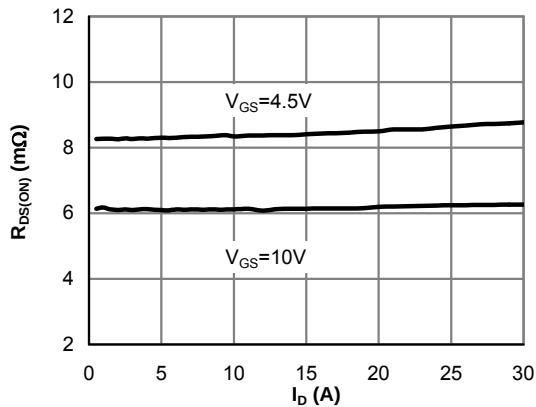


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

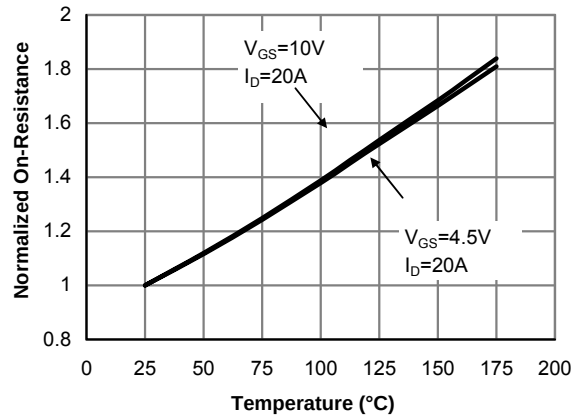


Figure 4: On-Resistance vs. Junction Temperature (Note E)

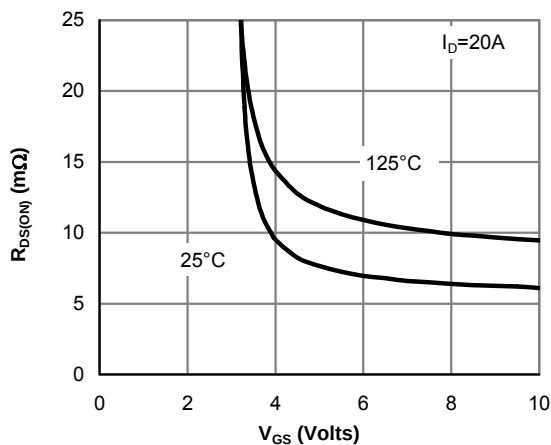


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

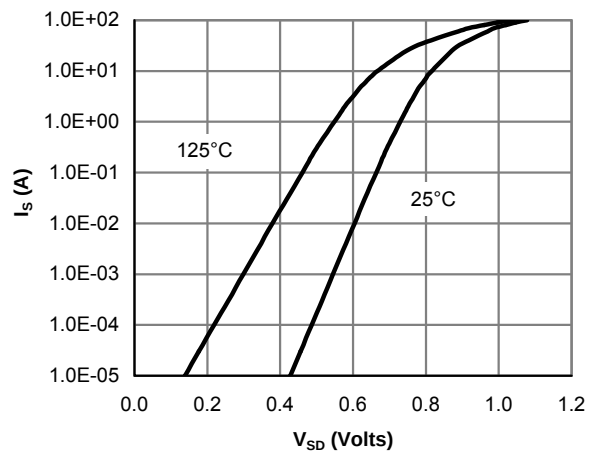
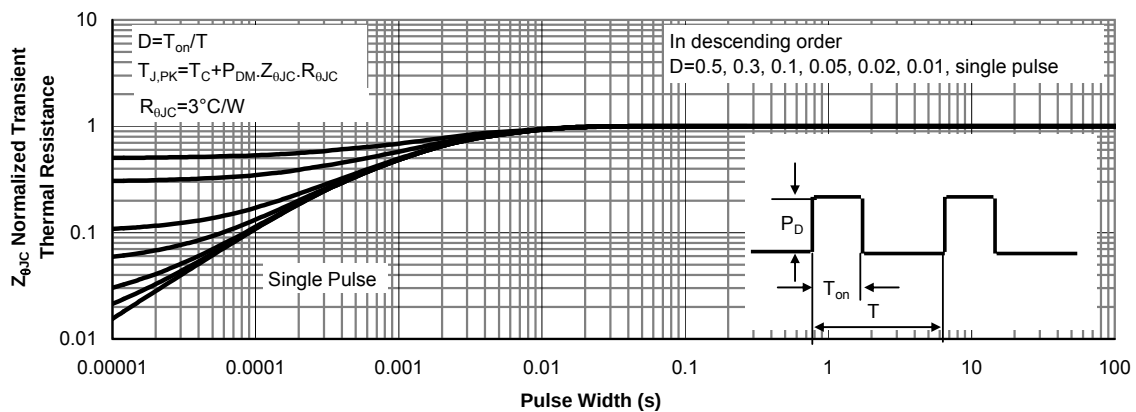
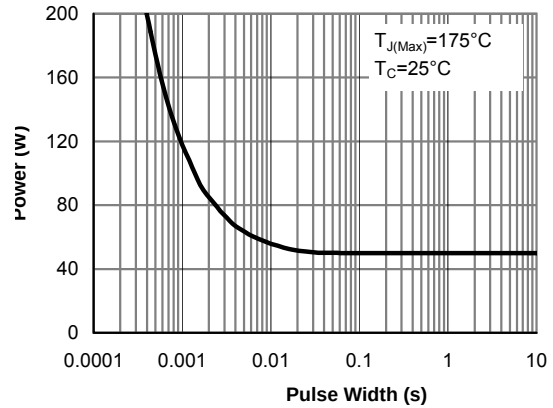
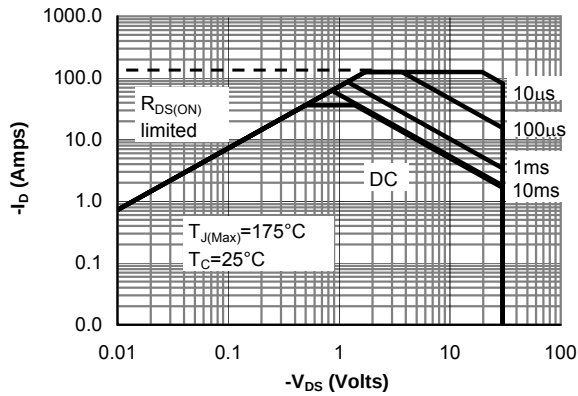
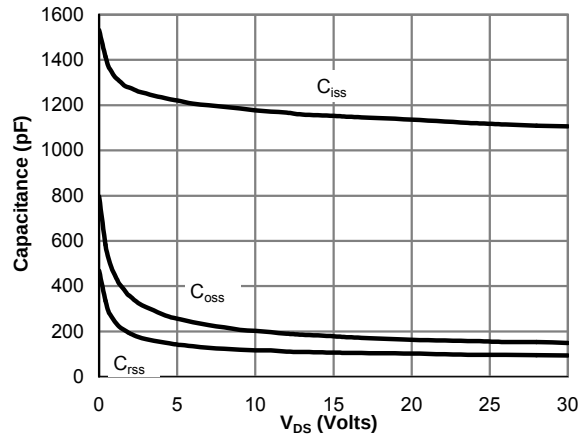
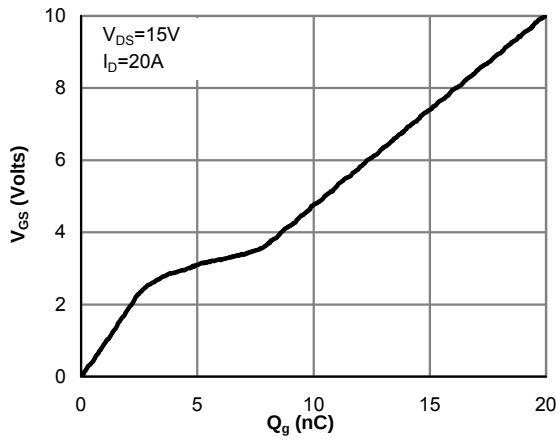


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



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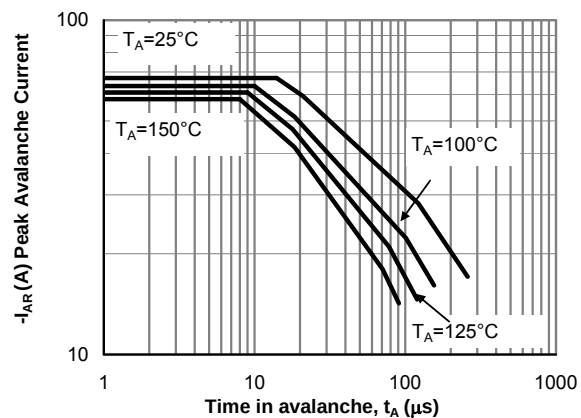


Figure 12: Single Pulse Avalanche capability (Note C)

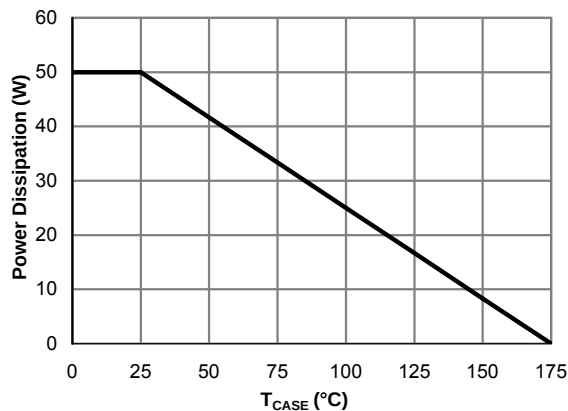


Figure 13: Power De-rating (Note F)

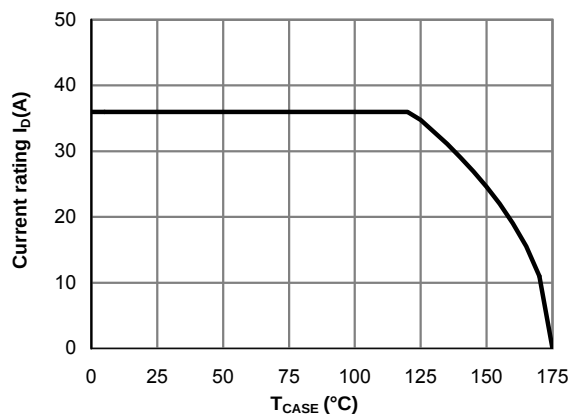


Figure 14: Current De-rating (Note F)

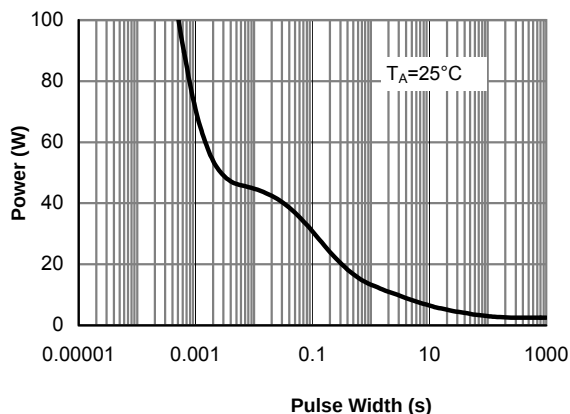


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

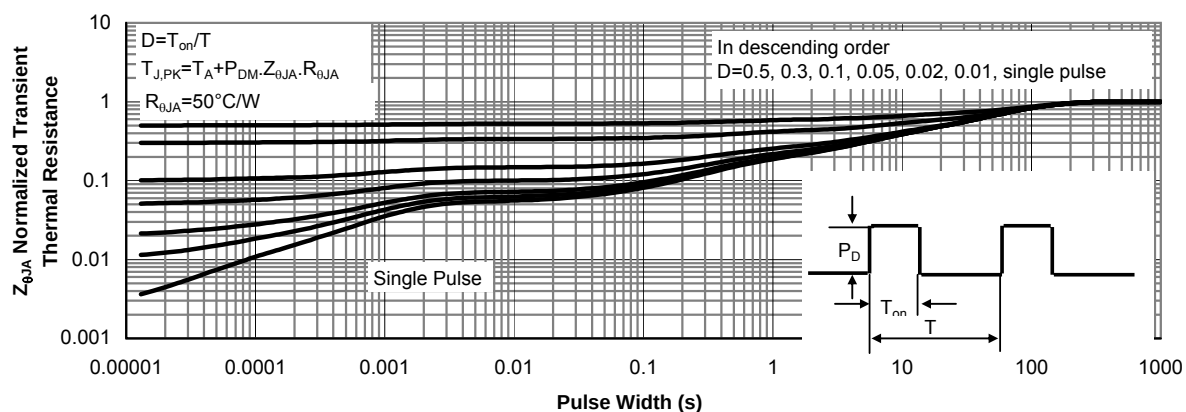
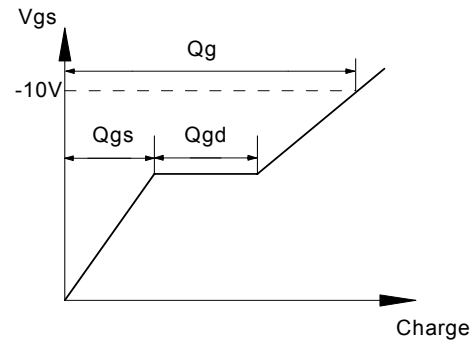
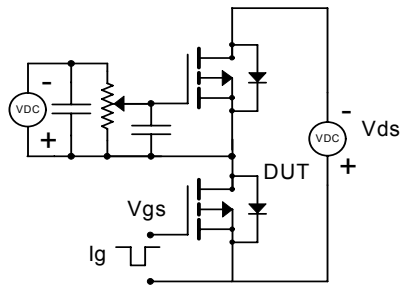
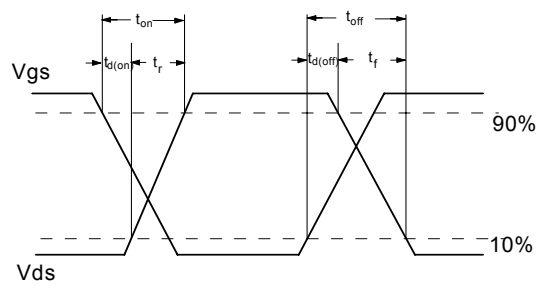
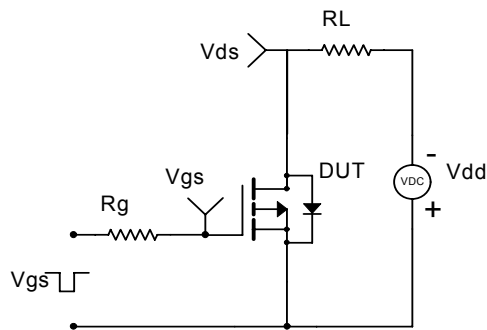


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)

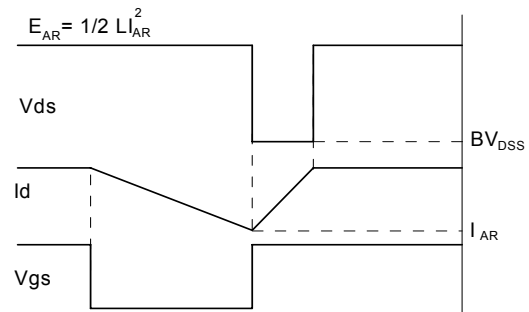
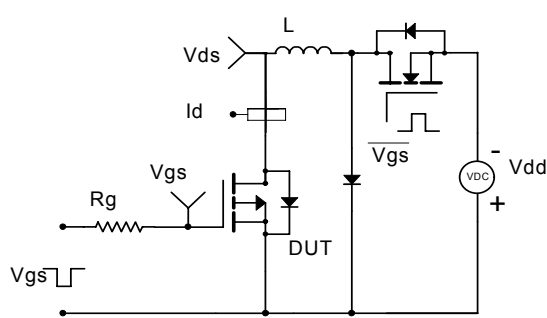
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

